

CLAIMS:

1. A dielectric paste adapted for forming a spacer layer and containing a butyral system resin as a binder and at least one solvent selected from a group consisting of dihydroterpinyl oxyethanol, terpinyl oxyethanol, d-dihydrocarveol, I-citronellol, I-perillyl alcohol and acetoxy-methoxyethoxy-cyclohexanol acetate as a solvent.
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2. A dielectric paste adapted for forming a spacer layer in accordance with Claim 1, wherein the degree of polymerization of the butyral system resin is equal to or larger than 1400 and equal to or smaller than 2600.
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3. A dielectric paste adapted for forming a spacer layer in accordance with Claim 1, wherein the degree of butyralization of the butyral system resin is equal to or larger than 64 mol % and equal to or smaller than 78 mol %.
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4. A dielectric paste adapted for forming a spacer layer in accordance with Claim 2, wherein the degree of butyralization of the butyral system resin is equal to or larger than 64 mol % and equal to or smaller than 78 mol %.
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